

RMA201 AU80-SN20 SOLDER PASTE

FEATURES

- ▶ Excellent Wetting
- ▶ Excellent Cleaning Window
- ▶ Superior Slump Resistance
- ▶ 6 Hour Tack Time
- ▶ Aqueous Clean With Saponifier
- ▶ Large Process Window

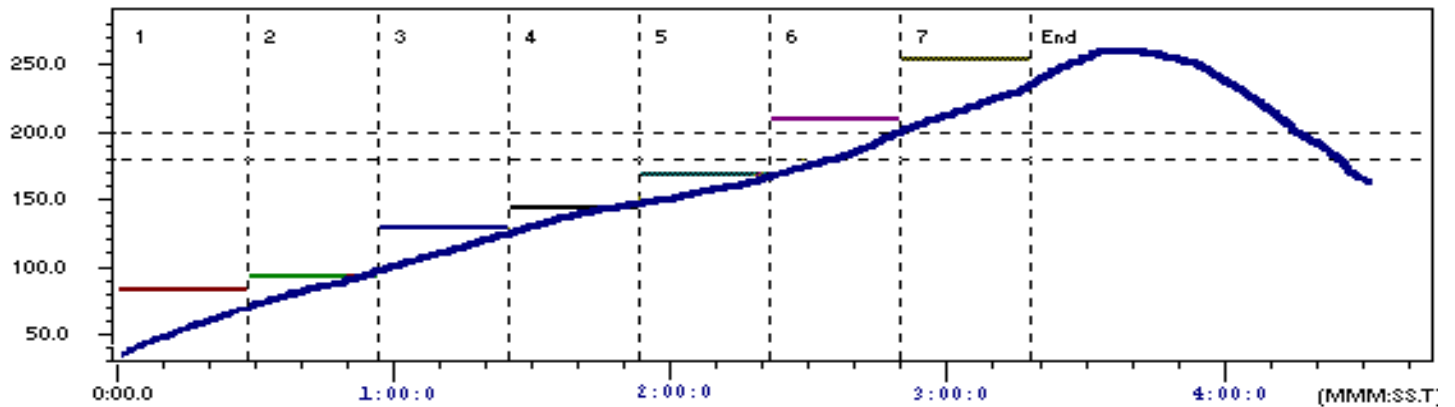
DESCRIPTION

RMA201 is a mildly activated, pure gum rosin solder paste that is QQS571 E, QPL approved. The RMA201 formulation is designed specifically to allow reflow at higher than normal temperatures. Post-process residues have undergone testing to insure high insulation resistance, and may be left on the PCB without degradation. Flux activity is adequate to wet most metal surfaces used on electronic circuit boards. RMA201 has a wide process window, and will accommodate a large variety of environments and process applications. This product performs well in continuous production, offering good slump resistance, high tack, and low post-process residues.

STANDARD PASTE COMPOSITION

Application Method	IPC Powder Size	Metal Load
Standard Stencil Printing	3	90%
Fine Pitch Stencil Printing	5	89.5%
Ultra-Fine Pitch Stencil Printing	5	89%
Dispensing Syringes	3	85.5%

REFLOW PROFILE



Rate of Rise 1-2° C / Sec Max	Pre-Heat Ramp to 150°C	Continue Through 150° C-175°C	To Peak Temp 300° C ± 5°C	Time Above 281° C	Cooldown ≤ 4° C / SEC
-	≤ 146 Sec	10-30 Sec	-	60 ± 15 Sec	-

Document Rev # NF1
Page 1 of 2

DISCLAIMER The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to <http://www.aimsolder.com/terms-conditions> to review AIM's terms and conditions.

PRINTER SETUP

Recommended Initial Printer Settings – Dependent on PCB and Pad Design	
Parameter	Recommended Initial Settings
Squeegee Pressure	1 – 1.5 lbs/inch of blade
Squeegee Speed	.5 – 6 inches/second
Snap-off Distance	On Contact 0.00 mm
PCB Separation Distance	0.030 - .050”
PCB Separation Speed	Medium

PASTE APPLICATION

Apply sufficient paste to the stencil to allow a smooth, even roll during the print cycle. A bead diameter of 1/2 to 5/8 inch is normally sufficient to begin. Apply small amounts of fresh solder paste to the stencil at frequent, controlled intervals to maintain paste chemistry and workable properties. Cleaning of your stencil will vary according to the application; however, it can be accomplished using AIM DJAW stencil cleaner. Use DJAW in moderation and remove any excess cleaner from stencil.

PLACEMENT INFORMATION

RMA201 provides the necessary tack time/force for today’s high-speed placement equipment. Ensuring proper support of PCBs during assembly and handling will enhance product performance and reliability.

HANDLING & STORAGE

- RMA201 has a refrigerated shelf life of 1 year at 4°C or 40°F, and non-refrigerated shelf life of 6 months at 22°C or 70°F. Do not freeze this product.
- Allow the solder paste to completely warm naturally to ambient temperature (8 hours is recommended) prior to breaking seal for use.
- Mix the product lightly and thoroughly for 1 to 2 minutes to ensure even distribution of any separated material resulting from storage.
- Do not store new and used paste in the same container. Re-seal any opened containers while not in use.
- Replace the internal plug in conjunction with the cap of the 500 gram jar to ensure the best possible seal.

CLEANING

RMA201 can be cleaned if necessary, with saponified tap water. We recommend AIMTERGE 520; however, deionized water is recommended for the final rinse. A temperature of 100 - 150°F is sufficient for removing any residues. An in-line or other pressurized spray cleaning system is suggested, but is not required.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Material Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.